IN THE SPECIFICATION:

Please replace paragraph number **[0022]** with the following rewritten paragraph:

**[0022]** FIGS. ~~2A—2D~~ 2A-2D are cross-sectional views illustrating the screen printing of an exemplary conductive trace on a portion of a representative microelectronic component in accordance with the present invention;

Please replace paragraph number **[0024]** with the following rewritten paragraph:

**[0024]** FIG. 3B is a cross-sectional view taken along line ~~3B—3B~~ 3B-3B of a selected portion of the representative microelectronic component illustrated in FIG. 3A;

Please replace paragraph number **[0034]** with the following rewritten paragraph:

**[0034]** Preferably, screen 30 is formed of an interwoven mesh material such as fine diameter stainless steel wire or a monofilament polyester which has been woven to have a fine mesh value ranging from approximately 80 to approximately 500 mesh. Typically, the fine steel wire or polyester filament will have a nominal diameter ranging from approximately .2 mils to approximately .8 mils (.0002 inches/.0005 cm to .0008 inches/.0020 cm) with an approximate mesh range of ~~80—500~~ 80-500. Screens of suitable material and mesh are commercially available from a number of manufacturers, including Rigsby Screen and Stencil, Inc., Torrance, California; Utz Engineering, San Marcos, California; and Micro-Screen, South Bend, Indiana.

Please replace paragraph number **[0045]** with the following rewritten paragraph:

**[0045]** Illustrated in drawing FIG. 3B is a representative cross-sectional view of anode plate 44 as taken along line ~~3B—3B~~ 3B-3B of drawing FIG. 3A. In the cross-sectional view of drawing FIG. 3B, conductive trace 42, having a nominal vertical thickness of t, extends from the left edge of substrate 2, extends over the top-most surface of layer 6, which, as previously described, in combination with layer 4, comprises insulative spacer 3 having a preselected height H. Oppositely positioned spacer 7, comprised of layers 4 and 6, is located on the right

side of substrate 2 as shown in drawing FIGS. 3A and 3B and will usually be provided with the same preselected height H so that a complementary cathode plate 50 will be positioned so as to span across the insulative spacers 3 and 7 as shown in a simplified manner in the perspective view of drawing FIG. 8, making electrical contact with the various contact portions of conductive traces 42, including end traces 42A and 42B, having respectively shaped geometries for alignment purposes, located atop layer 6 of spacer 3. In operation, transparent area 45 will ultimately serve as the viewing window for the FED device. Optional contact pads can be provided on top of spacer 7 (not shown) if desired. Furthermore, oppositely positioned conductive traces could be disposed on spacer 7 in accordance with the present invention.